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(54) **SUBSTRATE HEATER AND SUBSTRATE PROCESSING APPARATUS INCLUDING THE SAME**

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**ABSTRACT**

Provided is a substrate heater including a support plate configured to be loaded with a substrate, an insulating layer arranged under the support plate, and a heating portion arranged under the insulating layer and configured to heat the support plate, wherein the insulating layer includes a plurality of layers, wherein at least two of the plurality of layers of the insulating layer have different thermal expansion coefficients from each other.

